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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Active
Number of LABs/CLBs	963
Number of Logic Elements/Cells	15408
Total RAM Bits	516096
Number of I/O	81
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP Exposed Pad
Supplier Device Package	144-EQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce15e22c8

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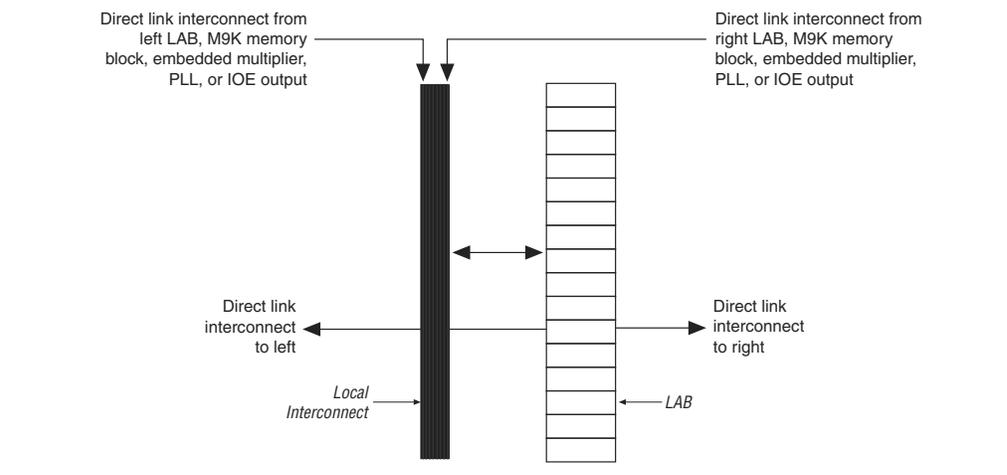
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LAB Interconnects

The LAB local interconnect is driven by column and row interconnects and LE outputs in the same LAB. Neighboring LABs, phase-locked loops (PLLs), M9K RAM blocks, and embedded multipliers from the left and right can also drive the local interconnect of a LAB through the direct link connection. The direct link connection feature minimizes the use of row and column interconnects, providing higher performance and flexibility. Each LE can drive up to 48 LEs through fast local and direct link interconnects.

Figure 2-5 shows the direct link connection.

Figure 2-5. Cyclone IV Device Direct Link Connection



LAB Control Signals

Each LAB contains dedicated logic for driving control signals to its LEs. The control signals include:

- Two clocks
- Two clock enables
- Two asynchronous clears
- One synchronous clear
- One synchronous load

You can use up to eight control signals at a time. Register packing and synchronous load cannot be used simultaneously.

Each LAB can have up to four non-global control signals. You can use additional LAB control signals as long as they are global signals.

Synchronous clear and load signals are useful for implementing counters and other functions. The synchronous clear and synchronous load signals are LAB-wide signals that affect all registers in the LAB.

Table 5-2. GCLK Network Connections for EP4CGX30, EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 Devices ⁽¹⁾, ⁽²⁾ (Part 4 of 4)

GCLK Network Clock Sources	GCLK Networks																													
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29
DPCLK17	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	—	—	—	—	—	—	—	—

Notes to Table 5-2:

- (1) EP4CGX30 information in this table refers to only EP4CGX30 device in F484 package.
- (2) PLL_1, PLL_2, PLL_3, and PLL_4 are general purpose PLLs while PLL_5, PLL_6, PLL_7, and PLL_8 are multipurpose PLLs.
- (3) PLL_7 and PLL_8 are not available in EP4CGX30, EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices in F484 package.

Table 5-3. GCLK Network Connections for Cyclone IV E Devices ⁽¹⁾ (Part 1 of 3)

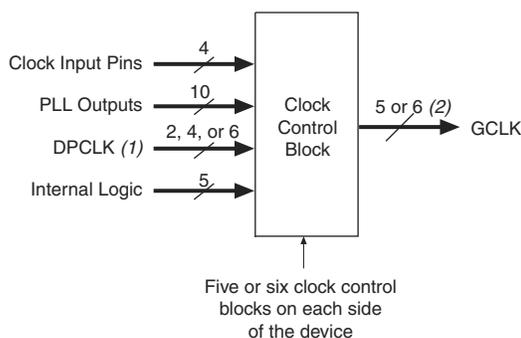
GCLK Network Clock Sources	GCLK Networks																			
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19
CLK1	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CLK2/DIFFCLK_1p	—	✓	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CLK3/DIFFCLK_1n	✓	—	—	✓	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CLK4/DIFFCLK_2p	—	—	—	—	—	✓	—	✓	—	✓	—	—	—	—	—	—	—	—	—	—
CLK5/DIFFCLK_2n	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—
CLK6/DIFFCLK_3p	—	—	—	—	—	—	✓	—	✓	✓	—	—	—	—	—	—	—	—	—	—
CLK7/DIFFCLK_3n	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—	—	—	—	—	—
CLK8/DIFFCLK_5n ⁽²⁾	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—	✓	—	—	—	—	—
CLK9/DIFFCLK_5p ⁽²⁾	—	—	—	—	—	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	—
CLK10/DIFFCLK_4n ⁽²⁾	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	✓	—	—	—	—	—
CLK11/DIFFCLK_4p ⁽²⁾	—	—	—	—	—	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—
CLK12/DIFFCLK_7n ⁽²⁾	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—	✓
CLK13/DIFFCLK_7p ⁽²⁾	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	✓	—	—
CLK14/DIFFCLK_6n ⁽²⁾	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	✓

From the clock sources listed above, only two clock input pins, two out of four PLL clock outputs (two clock outputs from either adjacent PLLs), one DPCLK pin, and one source from internal logic can drive into any given clock control block, as shown in Figure 5-1 on page 5-11.

Out of these six inputs to any clock control block, the two clock input pins and two PLL outputs are dynamically selected to feed a GCLK. The clock control block supports static selection of the signal from internal logic.

Figure 5-5 shows a simplified version of the clock control blocks on each side of the Cyclone IV GX device periphery.

Figure 5-5. Clock Control Blocks on Each Side of Cyclone IV GX Device



Notes to Figure 5-5:

- (1) The EP4CGX15 device has two DPCLK pins; the EP4CGX22 and EP4CGX30 devices have four DPCLK pins; the EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices have six DPCLK pins.
- (2) Each clock control block in the EP4CGX15, EP4CGX22, and EP4CGX30 devices can drive five GCLK networks. Each clock control block in the EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices can drive six GCLK networks.

The inputs to the five clock control blocks on each side of the Cyclone IV E device must be chosen from among the following clock sources:

- Three or four clock input pins, depending on the specific device
- Five PLL counter outputs
- Two DPCLK pins and two CDPCLK pins from both the left and right sides and four DPCLK pins from both the top and bottom
- Five signals from internal logic

From the clock sources listed above, only two clock input pins, two PLL clock outputs, one DPCLK or CDPCLK pin, and one source from internal logic can drive into any given clock control block, as shown in Figure 5-1 on page 5-11.

Out of these six inputs to any clock control block, the two clock input pins and two PLL outputs are dynamically selected to feed a GCLK. The clock control block supports static selection of the signal from internal logic.

Table 6-2 on page 6-7 shows the possible settings for I/O standards with current strength control. These programmable current strength settings are a valuable tool in helping decrease the effects of simultaneously switching outputs (SSO) in conjunction with reducing system noise. The supported settings ensure that the device driver meets the specifications for I_{OH} and I_{OL} of the corresponding I/O standard.

 When you use programmable current strength, on-chip series termination (R_S OCT) is not available.

Slew Rate Control

The output buffer for each Cyclone IV I/O pin provides optional programmable output slew-rate control. Table 6-2 on page 6-7 shows the possible slew rate option and the Quartus II default slew rate setting. However, these fast transitions may introduce noise transients in the system. A slower slew rate reduces system noise, but adds a nominal delay to rising and falling edges. Because each I/O pin has an individual slew-rate control, you can specify the slew rate on a pin-by-pin basis. The slew-rate control affects both the rising and falling edges. Slew rate control is available for single-ended I/O standards with current strength of 8 mA or higher.

 You cannot use the programmable slew rate feature when using OCT with calibration.

 You cannot use the programmable slew rate feature when using the 3.0-V PCI, 3.0-V PCI-X, 3.3-V LVTTTL, or 3.3-V LVCMOS I/O standards. Only the fast slew rate (default) setting is available.

Open-Drain Output

Cyclone IV devices provide an optional open-drain (equivalent to an open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (for example, interrupt and write enable signals) that are asserted by multiple devices in your system.

Bus Hold

Each Cyclone IV device user I/O pin provides an optional bus-hold feature. The bus-hold circuitry holds the signal on an I/O pin at its last-driven state. Because the bus-hold feature holds the last-driven state of the pin until the next input signal is present, an external pull-up or pull-down resistor is not necessary to hold a signal level when the bus is tri-stated.

The bus-hold circuitry also pulls undriven pins away from the input threshold voltage in which noise can cause unintended high-frequency switching. You can select this feature individually for each I/O pin. The bus-hold output drives no higher than V_{CCIO} to prevent overdriving signals.

 If you enable the bus-hold feature, the device cannot use the programmable pull-up option. Disable the bus-hold feature when the I/O pin is configured for differential signals. Bus-hold circuitry is not available on dedicated clock pins.

Bus-hold circuitry is only active after configuration. When going into user mode, the bus-hold circuit captures the value on the pin present at the end of configuration.

When designing LVTTTL/LVCMOS inputs with Cyclone IV devices, refer to the following guidelines:

- All pins accept input voltage (V_I) up to a maximum limit (3.6 V), as stated in the recommended operating conditions provided in the *Cyclone IV Device Datasheet* chapter.
- Whenever the input level is higher than the bank V_{CCIO} , expect higher leakage current.
- The LVTTTL/LVCMOS I/O standard input pins can only meet the V_{IH} and V_{IL} levels according to bank voltage level.

Voltage-referenced standards are supported in an I/O bank using any number of single-ended or differential standards, as long as they use the same V_{REF} and V_{CCIO} values. For example, if you choose to implement both SSTL-2 and SSTL-18 in your Cyclone IV devices, I/O pins using these standards—because they require different V_{REF} values—must be in different banks from each other. However, the same I/O bank can support SSTL-2 and 2.5-V LVCMOS with the V_{CCIO} set to 2.5 V and the V_{REF} set to 1.25 V.

 When using Cyclone IV devices as a receiver in 3.3-, 3.0-, or 2.5-V LVTTTL/LVCMOS systems, you are responsible for managing overshoot or undershoot to stay in the absolute maximum ratings and the recommended operating conditions, provided in the *Cyclone IV Device Datasheet* chapter.

 The PCI clamping diode is enabled by default in the Quartus II software for input signals with bank V_{CCIO} at 2.5, 3.0, or 3.3 V.

High-Speed Differential Interfaces

Cyclone IV devices can send and receive data through LVDS signals. For the LVDS transmitter and receiver, the input and output pins of Cyclone IV devices support serialization and deserialization through internal logic.

The BLVDS extends the benefits of LVDS to multipoint applications such as bidirectional backplanes. The loading effect and the need to terminate the bus at both ends for multipoint applications require BLVDS to drive out a higher current than LVDS to produce a comparable voltage swing. All the I/O banks of Cyclone IV devices support BLVDS for user I/O pins.

The RSDS and mini-LVDS standards are derivatives of the LVDS standard. The RSDS and mini-LVDS I/O standards are similar in electrical characteristics to LVDS, but have a smaller voltage swing and therefore provide increased power benefits and reduced electromagnetic interference (EMI).

The PPDS standard is the next generation of the RSDS standard introduced by National Semiconductor Corporation. Cyclone IV devices meet the National Semiconductor Corporation PPDS Interface Specification and support the PPDS standard for outputs only. All the I/O banks of Cyclone IV devices support the PPDS standard for output pins only.

The LVDS standard does not require an input reference voltage, but it does require a 100- Ω termination resistor between the two signals at the input buffer. An external resistor network is required on the transmitter side for the top and bottom I/O banks.

 For more information about Cyclone IV PLL, refer to the *Clock Networks and PLLs in Cyclone IV Devices* chapter.

Document Revision History

Table 7-3 lists the revision history for this chapter.

Table 7-3. Document Revision History

Date	Version	Changes
March 2016	2.6	<ul style="list-style-type: none"> ■ Updated Table 7-1 to remove support for the N148 package. ■ Updated note (1) in Figure 7-2 to remove support for the N148 package. ■ Updated Figure 7-4 to remove support for the N148 package.
May 2013	2.5	Updated Table 7-2 to add new device options and packages.
February 2013	2.4	Updated Table 7-2 to add new device options and packages.
October 2012	2.3	Updated Table 7-1 and Table 7-2.
December 2010	2.2	<ul style="list-style-type: none"> ■ Updated for the Quartus II software version 10.1 release. ■ Added Cyclone IV E new device package information. ■ Updated Table 7-2. ■ Minor text edits.
November 2010	2.1	Updated “Data and Data Clock/Strobe Pins” section.
February 2010	2.0	<ul style="list-style-type: none"> ■ Added Cyclone IV E devices information for the Quartus II software version 9.1 SP1 release. ■ Updated Table 7-1. ■ Added Table 7-2. ■ Added Figure 7-5 and Figure 7-6.
November 2009	1.0	Initial release.

Section III. System Integration

This section includes the following chapters:

- Chapter 8, Configuration and Remote System Upgrades in Cyclone IV Devices
- Chapter 9, SEU Mitigation in Cyclone IV Devices
- Chapter 10, JTAG Boundary-Scan Testing for Cyclone IV Devices
- Chapter 11, Power Requirements for Cyclone IV Devices

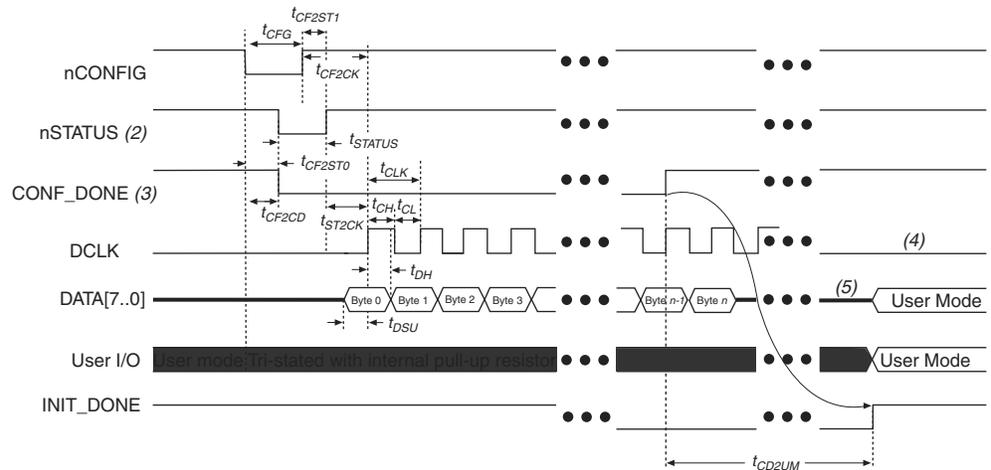
Revision History

Refer to each chapter for its own specific revision history. For information on when each chapter was updated, refer to the Chapter Revision Dates section, which appears in the complete handbook.

FPP Configuration Timing

Figure 8–22 shows the timing waveform for the FPP configuration when using an external host.

Figure 8–22. FPP Configuration Timing Waveform ⁽¹⁾



Notes to Figure 8–22:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power up, the Cyclone IV device holds nSTATUS low during POR delay.
- (3) After power up, before and during configuration, CONF_DONE is low.
- (4) Do not leave DCLK floating after configuration. It must be driven high or low, whichever is more convenient.
- (5) DATA [7..0] is available as a user I/O pin after configuration; the state of the pin depends on the dual-purpose pin settings.

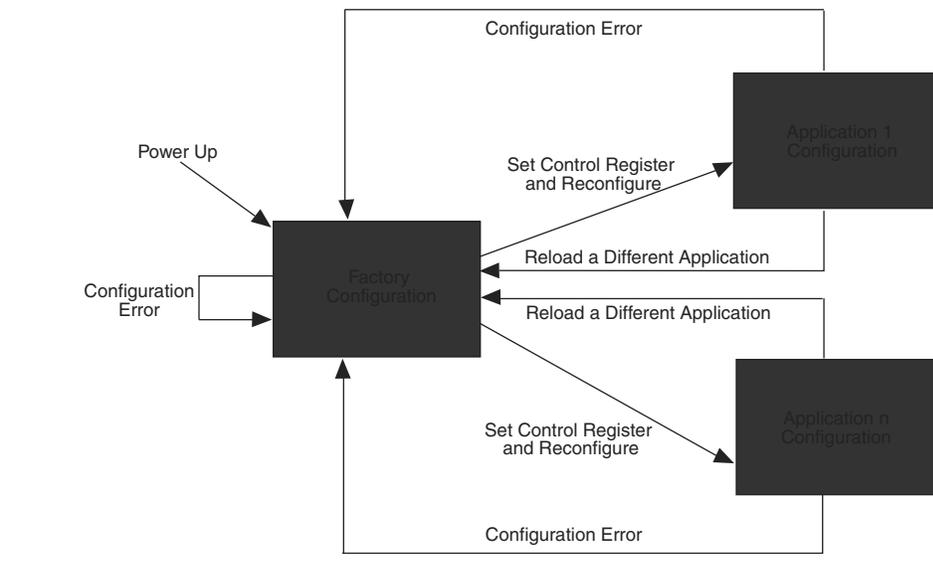
Table 8–13 lists the FPP configuration timing parameters for Cyclone IV devices.

Table 8–13. FPP Timing Parameters for Cyclone IV Devices (Part 1 of 2)

Symbol	Parameter	Minimum		Maximum		Unit
		Cyclone IV ⁽¹⁾	Cyclone IV E ⁽²⁾	Cyclone IV ⁽¹⁾	Cyclone IV E ⁽²⁾	
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	—	500	—	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	—	500	—	ns
t _{CFG}	nCONFIG low pulse width	500	—	—	—	ns
t _{STATUS}	nSTATUS low pulse width	45	—	230 ⁽³⁾	—	μs
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	—	230 ⁽⁴⁾	—	μs
t _{CF2CK}	nCONFIG high to first rising edge on DCLK	230 ⁽³⁾	—	—	—	μs

Figure 8–32 shows the transitions between the factory configuration and application configuration in remote update mode.

Figure 8–32. Transitions Between Configurations in Remote Update Mode



After power up or a configuration error, the factory configuration logic writes the remote system upgrade control register to specify the address of the application configuration to be loaded. The factory configuration also specifies whether or not to enable the user watchdog timer for the application configuration and, if enabled, specifies the timer setting.

 Only valid application configurations designed for remote update mode include the logic to reset the timer in user mode. For more information about the user watchdog timer, refer to the “User Watchdog Timer” on page 8–79.

If there is an error while loading the application configuration, the remote system upgrade status register is written by the dedicated remote system upgrade circuitry of the Cyclone IV device to specify the cause of the reconfiguration.

The following actions cause the remote system upgrade status register to be written:

- nSTATUS driven low externally
- Internal cyclical redundancy check (CRC) error
- User watchdog timer time-out
- A configuration reset (logic array nCONFIG signal or external nCONFIG pin assertion)

The Cyclone IV device automatically loads the factory configuration when an error occurs. This user-designed factory configuration reads the remote system upgrade status register to determine the reason for reconfiguration. Then the factory configuration takes the appropriate error recovery steps and writes to the remote system upgrade control register to determine the next application configuration to be loaded.

Document Revision History

Table 10-3 lists the revision history for this chapter.

Table 10-3. Document Revision History

Date	Version	Changes
December 2013	1.3	■ Updated the “EXTEST_PULSE” section.
November 2011	1.2	■ Updated the “BST Operation Control” section. ■ Updated Table 10-2.
February 2010	1.1	■ Added Cyclone IV E devices in Table 10-1 and Table 10-2 for the Quartus II software version 9.1 SP1 release. ■ Updated Figure 10-1 and Figure 10-2. ■ Minor text edits.
November 2009	1.0	Initial release.

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Additional Information

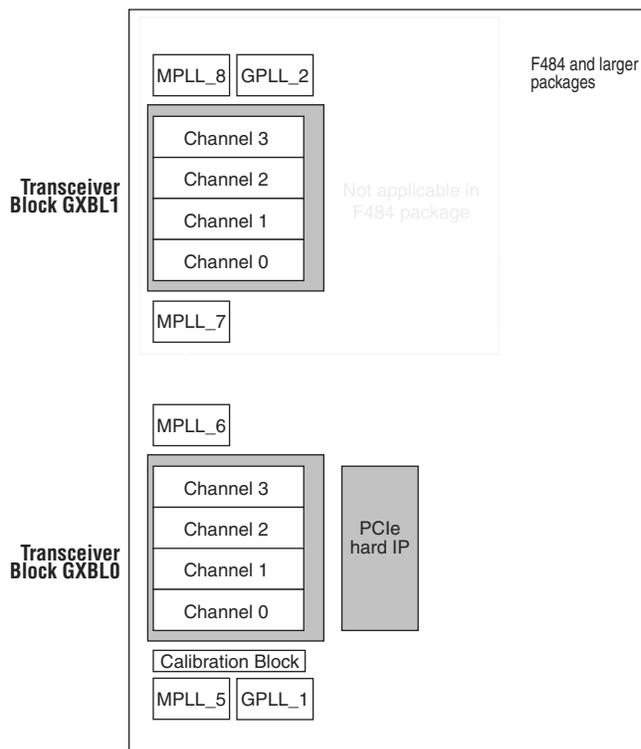
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Section I. Transceivers

Chapter 1. Cyclone IV Transceivers Architecture

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Figure 1–2. F484 and Larger Packages with Transceiver Channels for Cyclone IV GX Devices



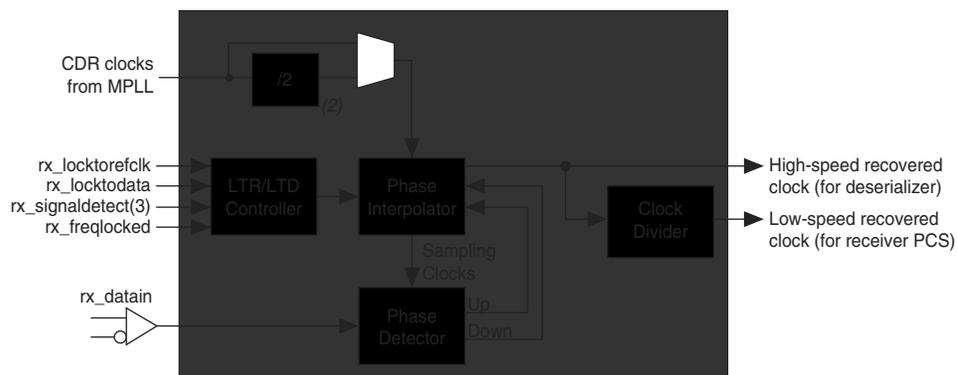
For more information about the transceiver architecture, refer to the following sections:

- “Architectural Overview” on page 1–4
- “Transmitter Channel Datapath” on page 1–5
- “Receiver Channel Datapath” on page 1–11
- “Transceiver Clocking Architecture” on page 1–26
- “Transceiver Channel Datapath Clocking” on page 1–29
- “FPGA Fabric-Transceiver Interface Clocking” on page 1–43
- “Calibration Block” on page 1–45
- “PCI-Express Hard IP Block” on page 1–46

Clock Data Recovery

Each receiver channel has an independent CDR unit to recover the clock from the incoming serial data stream. The high-speed recovered clock is used to clock the deserializer for serial-to-parallel conversion of the received input data, and low-speed recovered clock to clock the receiver PCS blocks. Figure 1-15 illustrates the CDR unit block diagram.

Figure 1-15. CDR Unit Block Diagram



Notes to Figure 1-15:

- (1) Optional RX local divider for CDR clocks from multipurpose PLL is only available in each CDR unit for EP4CGX30 (F484 package), EP4CGX50, and EP4CGX75 devices. This block is used with the transceiver dynamic reconfiguration feature. For more information, refer to the *Cyclone IV Dynamic Reconfiguration* chapter and *AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices*.
- (2) CDR state transition in automatic lock mode is not dependent on rx_signaldetect signal, except when configured in PCI Express (PIPE) mode only.

Each CDR unit gets the reference clock from one of the two multipurpose phase-locked loops (PLLs) adjacent to the transceiver block. The CDR works by tracking the incoming data with a phase detector and finding the optimum sampling clock phase from the phase interpolator unit. The CDR operations are controlled by the LTR/LTD controller block, where the CDR may operate in the following states:

- Lock-to-reference (LTR) state—phase detector disabled and CDR ignores incoming data
- Lock-to-data (LTD) state—phase detector enabled and CDR tracks incoming data to find the optimum sampling clock phase

State transitions are supported with automatic lock mode and manual lock mode.

Automatic Lock Mode

Upon receiver power-up and reset cycle, the CDR is put into LTR state. Transition to the LTD state is performed automatically when both of the following conditions are met:

- Signal detection circuitry indicates the presence of valid signal levels at the receiver input buffer. This condition is valid for PCI Express (PIPE) mode only. CDR transitions are not dependent on signal detection circuitry in other modes.
- The recovered clock is within the configured part per million (ppm) frequency threshold setting with respect to the CDR clocks from multipurpose PLL.

Clock Rate Compensation

In XAUI mode, the rate match FIFO compensates up to ± 100 ppm (200 ppm total) difference between the upstream transmitter and the local receiver reference clock. The XAUI protocol requires the transmitter to send /R/ (/K28.0/) code groups simultaneously on all four lanes (denoted as ||R|| column) during inter-packet gaps, adhering to rules listed in the IEEE P802.3ae specification.

The rate match operation begins after `rx_syncstatus` and `rx_channelaligned` are asserted. The `rx_syncstatus` signal is from the word aligner, indicating that synchronization is acquired on all four channels, while `rx_channelaligned` signal is from the deskew FIFO, indicating channel alignment.

The rate match FIFO looks for the ||R|| column (simultaneous /R/ code groups on all four channels) and deletes or inserts ||R|| columns to prevent the rate match FIFO from overflowing or under running. The rate match FIFO can insert or delete as many ||R|| columns as necessary to perform the rate match operation.

The `rx_rmfiodeleted` and `rx_rmfifoinserted` flags that indicate rate match FIFO deletion and insertion events, respectively, are forwarded to the FPGA fabric. If an ||R|| column is deleted, the `rx_rmfiodeleted` flag from each of the four channels goes high for one clock cycle per deleted ||R|| column. If an ||R|| column is inserted, the `rx_rmfifoinserted` flag from each of the four channels goes high for one clock cycle per inserted ||R|| column.

 The rate match FIFO does not insert or delete code groups automatically to overcome FIFO empty or full conditions. In this case, the rate match FIFO asserts the `rx_rmfifoempty` and `rx_rmfifofull` flags for at least three recovered clock cycles to indicate rate match FIFO full and empty conditions, respectively. You must then assert the `rx_digitalreset` signal to reset the receiver PCS blocks.

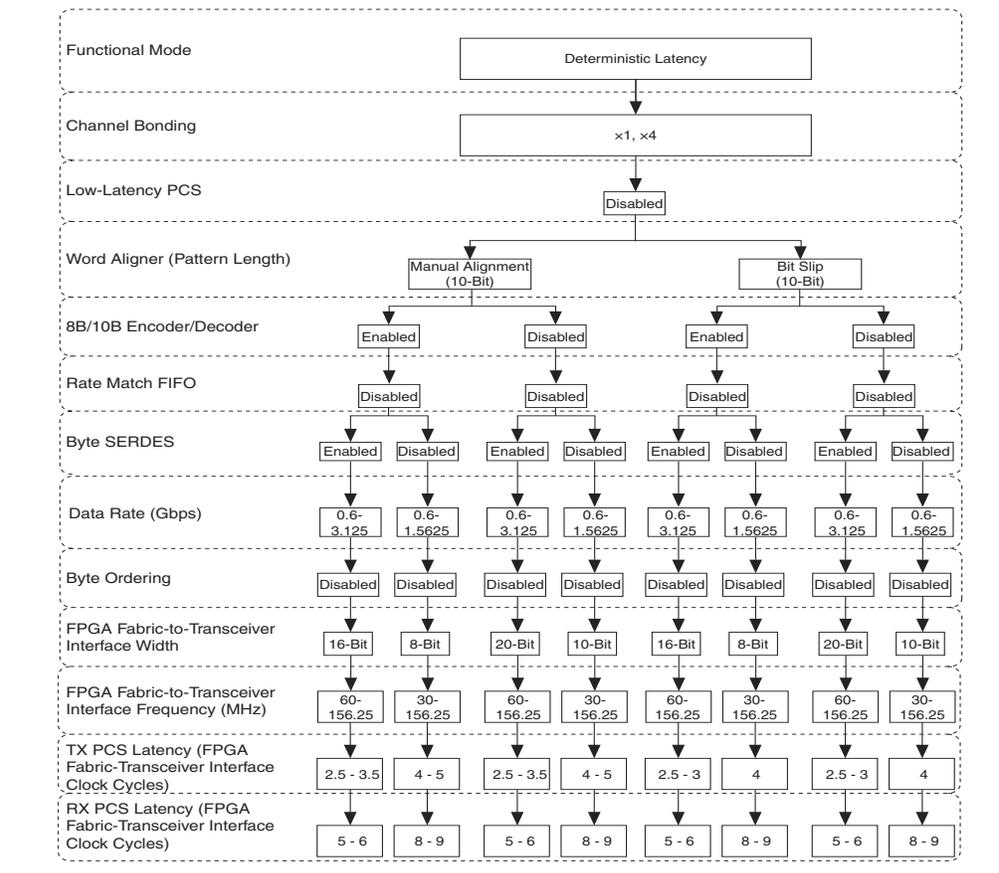
Deterministic Latency Mode

Deterministic Latency mode provides the transceiver configuration that allows no latency uncertainty in the datapath and features to strictly control latency variation. This mode supports non-bonded ($\times 1$) and bonded ($\times 4$) channel configurations, and is typically used to support CPRI and OBSAI protocols that require accurate delay measurements along the datapath. The Cyclone IV GX transceivers configured in Deterministic Latency mode provides the following features:

- registered mode phase compensation FIFO
- receive bit-slip indication
- transmit bit-slip control
- PLL PFD feedback

Figure 1-67 shows the transceiver configuration in Deterministic Latency mode.

Figure 1-67. Transceiver Configuration in Deterministic Latency Mode



Both CPRI and OBSAI protocols define the serial interface connecting the base station component (specifically channel cards) and remote radio heads (specifically radio frequency cards) in a radio base station system with fiber optics. The protocols require the accuracy of round trip delay measurement for single-hop and multi-hop connections to be within ± 16.276 ns. The Cyclone IV GX transceivers support the following CPRI and OBSAI line rates using Deterministic Latency mode:

- CPRI—614.4 Mbps, 1.2288 Gbps, 2.4576 Gbps, and 3.072 Gbps
- OBSAI—768 Mbps, 1.536 Gbps, and 3.072 Gbps

 For more information about deterministic latency implementation, refer to *AN 610: Implementing Deterministic Latency for CPRI and OBSAI Protocols in Stratix IV, HardCopy IV, Arria II GX, and Cyclone IV Devices*.

Registered Mode Phase Compensation FIFO

In Deterministic Latency mode, the RX phase compensation FIFO is set to registered mode while the TX phase compensation FIFO supports optional registered mode. When set into registered mode, the phase compensation FIFO acts as a register and eliminates the latency uncertainty through the FIFOs.

Document Revision History

Table 1-30 lists the revision history for this chapter.

Table 1-30. Document Revision History

Date	Version	Changes
February 2015	3.7	<ul style="list-style-type: none"> ■ Updated the GiGE row in Table 1-14. ■ Updated the “GIGE Mode” section. ■ Updated the note in the “Clock Frequency Compensation” section.
October 2013	3.6	Updated Figure 1-15 and Table 1-4.
May 2013	3.5	Updated Table 1-27 by setting “rx_locktodata” and “rx_locktorefclock” to “Input”
October 2012	3.4	<ul style="list-style-type: none"> ■ Updated the data rate for the V-by-one protocol and the F324 package support in HD-SDI in Table 1-1. ■ Updated note (1) to Figure 1-27. ■ Added latency information to Figure 1-67.
November 2011	3.3	<ul style="list-style-type: none"> ■ Updated “Word Aligner” and “Basic Mode” sections. ■ Updated Figure 1-37.
December 2010	3.2	<ul style="list-style-type: none"> ■ Updated for the Quartus II software version 10.1 release. ■ Updated Table 1-1, Table 1-5, Table 1-11, Table 1-14, Table 1-24, Table 1-25, Table 1-26, Table 1-27, Table 1-28, and Table 1-29. ■ Updated “8B/10B Encoder”, “Transmitter Output Buffer”, “Receiver Input Buffer”, “Clock Data Recovery”, “Miscellaneous Transmitter PCS Features”, “Miscellaneous Receiver PCS Feature”, “Input Reference Clocking”, “PCI Express (PIPE) Mode”, “Channel Deskewing”, “Lane Synchronization”, “Serial Loopback”, and “Self Test Modes” sections. ■ Added Figure 1-9, Figure 1-10, Figure 1-19, Figure 1-20, and Figure 1-43. ■ Updated Figure 1-53, Figure 1-55, Figure 1-59, Figure 1-60, Figure 1-69, Figure 1-70, Figure 1-71, Figure 1-72, Figure 1-73, and Figure 1-74.
November 2010	3.1	Updated Introductory information.
July 2010	3.0	<ul style="list-style-type: none"> ■ Updated information for the Quartus II software version 10.0 release. ■ Reset control, power down, and dynamic reconfiguration information moved to new <i>Cyclone IV Reset Control and Power Down</i> and <i>Cyclone IV Dynamic Reconfiguration</i> chapters.

PMA Control Ports Used in a Read Transaction

- tx_vodctrl_out is 3 bits per channel
- tx_preemp_out is 5 bits per channel
- rx_eqdcgain_out is 2 bits per channel
- rx_eqctrl_out is 4 bits per channel

For example, assume the number of channels controlled by the dynamic reconfiguration controller is two, tx_vodctrl_out is 6 bits wide.

Write Transaction

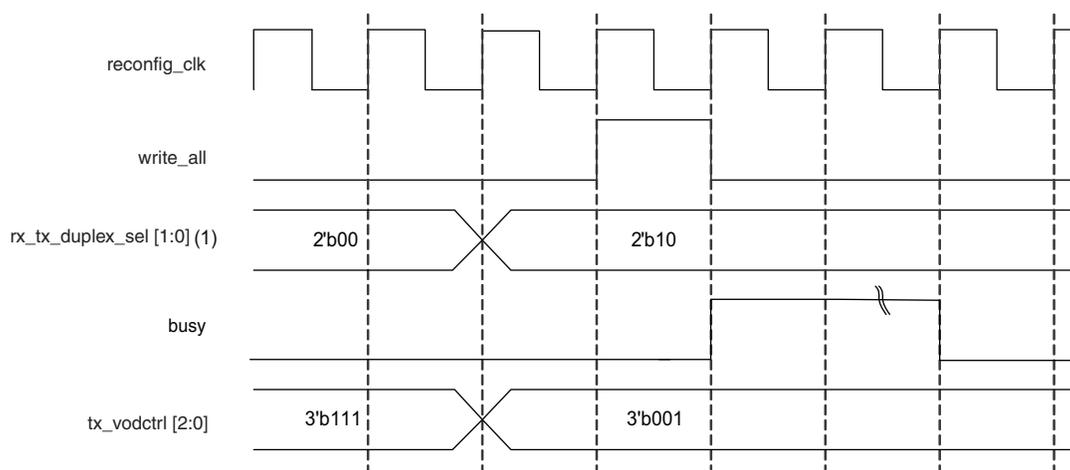
The value you set at the selected PMA control ports is written to all the transceiver channels connected to the ALTGX_RECONFIG instance.

For example, assume you have enabled tx_vodctrl in the ALTGX_RECONFIG MegaWizard Plug-In Manager to reconfigure the V_{OD} of the transceiver channels. To complete a write transaction to reconfigure the V_{OD}, perform the following steps:

1. Before you initiate a write transaction, set the selected PMA control ports to the desired settings (for example, tx_vodctrl = 3'b001).
2. Set the rx_tx_duplex_sel port to 2'b10 so that only the transmit PMA controls are written to the transceiver channel.
3. Ensure that the busy signal is low before you start a write transaction.
4. Assert the write_all signal for one reconfig_clk clock cycle. This initiates the write transaction.
5. The busy output status signal is asserted high to indicate that the dynamic reconfiguration controller is busy writing the PMA control values. When the write transaction has completed, the busy signal goes low.

Figure 3-6 shows the write transaction for Method 2.

Figure 3-6. Write Transaction Waveform—Use the same control signal for all the channels Option



Note to Figure 3-6:

(1) In this waveform example, you want to write to only the transmitter portion of the channel.

Table 1–29 lists the active configuration mode specifications for Cyclone IV devices.

Table 1–29. Active Configuration Mode Specifications for Cyclone IV Devices

Programming Mode	DCLK Range	Typical DCLK	Unit
Active Parallel (AP) ⁽¹⁾	20 to 40	33	MHz
Active Serial (AS)	20 to 40	33	MHz

Note to Table 1–29:

(1) AP configuration mode is only supported for Cyclone IV E devices.

Table 1–30 lists the JTAG timing parameters and values for Cyclone IV devices.

Table 1–30. JTAG Timing Parameters for Cyclone IV Devices ⁽¹⁾

Symbol	Parameter	Min	Max	Unit
t _{JCP}	TCK clock period	40	—	ns
t _{JCH}	TCK clock high time	19	—	ns
t _{JCL}	TCK clock low time	19	—	ns
t _{JPSU_TDI}	JTAG port setup time for TDI	1	—	ns
t _{JPSU_TMS}	JTAG port setup time for TMS	3	—	ns
t _{JPH}	JTAG port hold time	10	—	ns
t _{JPCO}	JTAG port clock to output ^{(2), (3)}	—	15	ns
t _{JPZX}	JTAG port high impedance to valid output ^{(2), (3)}	—	15	ns
t _{JPXZ}	JTAG port valid output to high impedance ^{(2), (3)}	—	15	ns
t _{JSSU}	Capture register setup time	5	—	ns
t _{JSH}	Capture register hold time	10	—	ns
t _{JSCO}	Update register clock to output	—	25	ns
t _{JSZX}	Update register high impedance to valid output	—	25	ns
t _{JSXZ}	Update register valid output to high impedance	—	25	ns

Notes to Table 1–30:

(1) For more information about JTAG waveforms, refer to “JTAG Waveform” in “Glossary” on page 1–37.

(2) The specification is shown for 3.3-, 3.0-, and 2.5-V LVTTTL/LVCMOS operation of JTAG pins. For 1.8-V LVTTTL/LVCMOS and 1.5-V LVCMOS, the output time specification is 16 ns.

(3) For EP4CGX22, EP4CGX30 (F324 and smaller package), EP4CGX110, and EP4CGX150 devices, the output time specification for 3.3-, 3.0-, and 2.5-V LVTTTL/LVCMOS operation of JTAG pins is 16 ns. For 1.8-V LVTTTL/LVCMOS and 1.5-V LVCMOS, the output time specification is 18 ns.

Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the high-speed I/O interface, external memory interface, and the PCI/PCI-X bus interface. I/Os using the SSTL-18 Class I termination standard can achieve up to the stated DDR2 SDRAM interfacing speeds. I/Os using general-purpose I/O standards such as 3.3-, 3.0-, 2.5-, 1.8-, or 1.5-LVTTTL/LVCMOS are capable of a typical 200 MHz interfacing frequency with a 10 pF load.